

JUL 19 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Tanya J. Snyder, Robert H. Yi, Robert E. Wilson
Assignee: Avago Technologies, Ltd.
Title: Wafer Bonding Using Reactive Foils For Massively Parallel Micro-Electromechanical Systems Packaging
Serial No.: 10/826,800 Filing Date: April 15, 2004
Examiner: David Nhu Group Art Unit: 2818
Docket No.: 10030280-4

San Jose, California
July 19, 2006

Mail Stop RCE
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

This is a response to the May 19, 2006 Final Office Action, which has a statutorily shortened period for response that ends on August 19, 2006. Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.